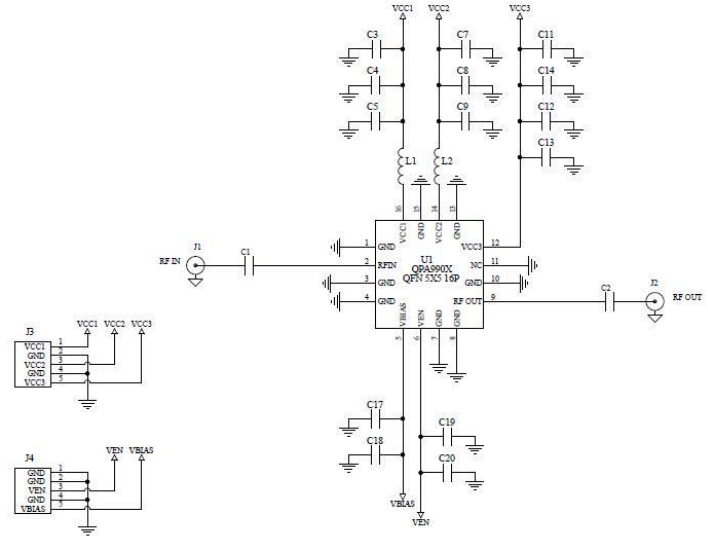
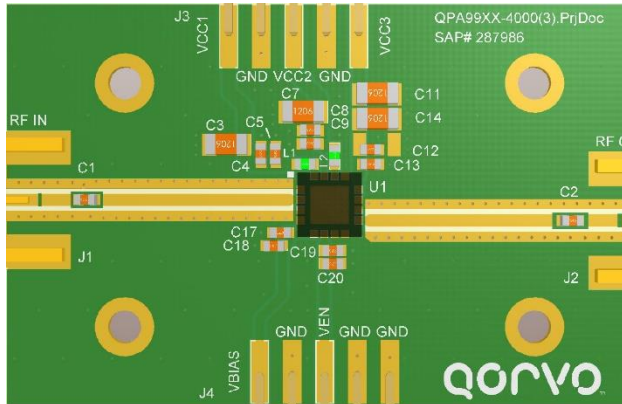


QPA9907 EVB Layout and Schematic



Bill of Materials – QPA9907EVB-01

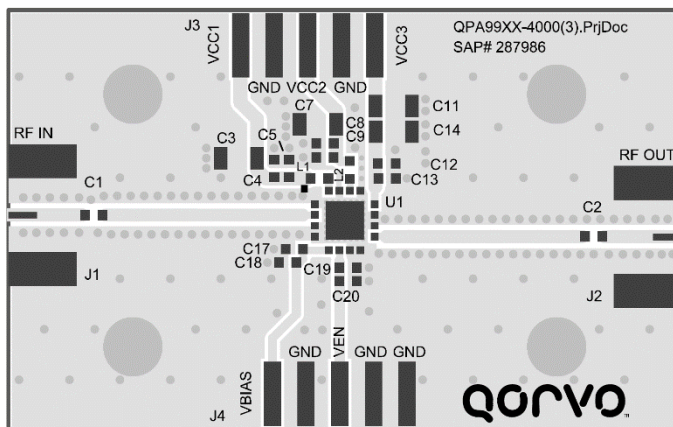
Reference Des.	Value	Description	Manufacturer	Part Number
U1	-	Amplifier, QPA9907 2500-2700MHz, High-Efficiency	Qorvo	QPA9907
C1, C2	100 pF	CAP,100 pF, 0603, 5%, 50V, NPO	various	
C5, C9, C13, C17, C19	1000 pF	CAP,1000 pF, 0603, 5%, 50V, NPO	various	
C4, C8, C12, C18, C20	0.1 μ F	CAP,0.1 μ F, 0603, 10%, 50V, X7R	various	
C3, C7, C14	10 μ F	CAP, 10 μ F, 1206, 16V	various	
L1, L2	0 Ω	RES 0 Ω , 0603, 1/16W, Chip	various	
J1, J2	-	CONN. RF. SMA. F. STRT. Edge Mount	various	
J3, J4	-	Connector, 5 Pin	various	

Evaluation Board PCB Information

PC Board Layout

Layer	Name	Material	Thickness	Constant
1	Top Overlay			
2	Top Solder	Solder Resist	0.40 mil	3.5
3	Top Layer	Copper	1.40 mil	
4	Dielectric1	RO4350	20.00 mil	3.48
5	Bottom Layer	Copper	1.40 mil	

Total thickness: 23.2mill



Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Via holes are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.10").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.